# 502630499 01/10/2014

### PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

EPAS ID: PAT2677107

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

### **CONVEYING PARTY DATA**

Name	Execution Date
KAI-YUAN TING	01/07/2014
SANDEEP KUMAR GOEL	01/07/2014
ASHOK MEHTA	01/07/2014

### **RECEIVING PARTY DATA**

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.		
Street Address:	NO. 8, LI-HSIN RD. 6, SCIENCE-BASED INDUSTRIAL PARK		
City:	HSIN-CHU		
State/Country:	TAIWAN		
Postal Code:	300-77		

# PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14152607

## **CORRESPONDENCE DATA**

**Fax Number**: (214)200-0853 **Phone**: 214-651-5000

Email: ipdocketing@haynesboone.com

Correspondence will be sent via US Mail when the email attempt is unsuccessful.

Correspondent Name: HAYNES AND BOONE, LLP IP SECTION

Address Line 1: 2323 VICTORY AVENUE

Address Line 2: SUITE 700

Address Line 4: DALLAS, TEXAS 75219

ATTORNEY DOCKET NUMBER:	24061.2679		
NAME OF SUBMITTER:	LINDA INGRAM		
Signature:	/Linda Ingram/		
	PATENT		

502630499 REEL: 031943 FRAME: 0122

Date:	01/10/2014
Total Attachments: 2 source=2679_Assignment#page1.tif source=2679_Assignment#page2.tif	

PATENT REEL: 031943 FRAME: 0123

Docket No.: 2013-1294 / 24061.2679

Customer No.: 000042717

### ASSIGNMENT

WHEREAS, we,

(1)	Kai-Yuan Ting	of	3150 Balmoral Drive San Jose, CA 95132, USA
(2)	Sandeep Kumar Goel	of	3420 Finnian Way, Unit 404 Dublin, CA 94568, USA
(3)	Ashok Mehta	of	501 Pine Wood Lane Los Gatos, CA 95032, USA

have invented certain improvements in

# SYSTEM AND METHOD OF ADAPTIVE VOLTAGE FREQUENCY SCALING

for which we have executed an application for Letters Patent of the United States of America,

of even date filed herewith; and

illustration filed on January 10, 2014, and assigned application number 14/152,607; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

R-353680\_1.docx - 1 -

2014/01/07 15:51:40 058169

Docket No.: 2013-1294 / 24061.2679

Customer No.: 000042717

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:

Kai-Yuan Ting

Residence Address:

3150 Balmoral Drive, San Jose, CA 95132, USA

Dated: Kar Jum (my 0/07/2

Inventor Signature

Inventor Name:

Sandeep Kumar Goel

Residence Address:

3420 Finnian Way, Unit 404, Dublin, CA 94568, USA

Date de

01/07/2014

Inventor Signature

Inventor Name:

Ashok Mehta

Residence Address:

501 Pine Wood Lane, Los Gatos, CA 95032, USA

- 2 -

Dated: Jan . 7, 2014

Inventor Signature

R-2679 - Assignment (1-7)

PATENT REEL: 031943 FRAME: 0125